Product Information Sheet

EPO-TEK® M10-D

Date:	September 2017	**Recommended Cure: B-stage cure: 75°C/30 Minutes**
Rev:	II	**Cure: 150°C/1 Hour**
No. of Components:	Single	
Mix Ratio by Weight:	N/A	
Specific Gravity:	1.35	
Pot Life:	2 Weeks (closed container)	**Dry Time**: > 1 Day
Shelf Life- Bulk:	One year refrigerated	

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, B-stageable epoxy paste for semiconductor, microelectronics, and optical assemblies. It can be used in hybrid assemblies for lid-sealing and substrate attach. In opto-packaging, it can be used as the main gasket seal of glass plates in LCDs, or for sealing filter windows onto opto-sensors.

Typical Properties: Cure condition: B-stage cure: 75°C/30 Minutes - Cure: 150°C/1 Hour Data below is not guaranteed.
Different batches, conditions & applications yield differing results. To be used as a guide only, not as a specification.
* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Tan	
* Consistency:	Slightly thixotropic paste	
* Viscosity (23°C) @ 50 rpm:	3,000 - 6,000	cPs
Thixotropic Index:	9.2	
Glass Transition Temp:	80	°C
Coefficient of Thermal Expansion (CTE):		
Below Tg:	35	x 10^{-6} in/in°C
Above Tg:	128	x 10^{-6} in/in°C
Shore D Hardness:	72	
Lap Shear @ 23°C:	580	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	370	°C
Weight Loss:		
@ 200°C:	1.31	%
@ 250°C:	2.76	%
@ 300°C:	5.75	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	576,738	psi
* Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	0.4	W/mK
Volume Resistivity @ 23°C:	≥ 5 x 10^{11}	Ohm-cm
Dielectric Constant (1KHz):	4.32	
Dissipation Factor (1KHz):	0.114	

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